

Electronic Patent Application Fee Transmittal

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|---|---|-----------------|---------------|-----------------------------|
| Application Number: | | | | |
| Filing Date: | | | | |
| Title of Invention: | SOLDER COMPOSITION AND METHOD OF BUMP FORMATION THEREWITH | | | |
| First Named Inventor: | Isao SAKAMOTO | | | |
| Filer: | Leslie J. Paperner/Ayako Asada | | | |
| Attorney Docket Number: | P30245 | | | |
| Filed as Large Entity | | | | |
| U.S. National Stage under 35 USC 371 Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| National Stage Fee | 1631 | 1 | 300 | 300 |
| Natl Stage Search Fee - Report provided | 1642 | 1 | 400 | 400 |
| National Stage Exam - all other cases | 1633 | 1 | 200 | 200 |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|-----------------------------------|----------|----------|--------|----------------------|
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |
| Miscellaneous: | | | | |
| Total in USD (\$) | | | | 900 |